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(19) **United States**(12) **Patent Application Publication****Suss et al.**(10) **Pub. No.: US 2023/0230871 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SUBSTRATE HOLDER DEVICE AND  
METHOD FOR BONDING****Publication Classification**(71) Applicant: **EV Group E. Thallner GmbH**, St.  
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(57)

**ABSTRACT**

The invention relates to a substrate holder device at least including at least one control valve and at least one substrate holder with a substrate holder surface and a substrate holder rear side. Furthermore, the invention relates to bonding device and a method for bonding.

